



PK598 (v1.0) February 15, 2013

100% Material Declaration Data Sheet for 7 Series CLG484 Package

Average Weight: 1.1360 g

| Component | Substance Description | CAS Number or Description | Percentage of Component | Use in Product | Component Weight/ Substance Weight (grams) | Component Percent of Total |
|----------------------------|----------------------------|---|-------------------------|----------------|--|----------------------------|
| Silicon Die | | | | | 0.025878 | 2.278 |
| | Silicon | 7440-21-3 | 100.00 | | 0.025878 | |
| Die Attach Material | | | | | 0.008105 | 0.713 |
| | Silver | 7440-22-4 | 77.50 | | 0.006281 | |
| | Bismaleimide monomer | Trade Secret | 15.00 | | 0.001216 | |
| | Acrylate monomer | Trade Secret | 7.50 | | 0.000608 | |
| Mold Compound | | | | | 0.476919 | 41.981 |
| | Epoxy Resin | Trade secret | 5.00 | | 0.023846 | |
| | Phenol Resin | Trade secret | 3.00 | | 0.014308 | |
| | Phenol Novolac | 9003-35-4 | 3.00 | | 0.014308 | |
| | Metal Hydroxide | Trade Secret | 3.00 | | 0.014308 | |
| | Carbon black | 1333-86-4 | 0.30 | | 0.001431 | |
| | Silica fused | 60676-86-0 | 70.40 | | 0.335751 | |
| | Silica Dioxide | 7631-86-9 | 15.00 | | 0.071538 | |
| | Silica, crystalline | 14808-60-7 | 0.30 | | 0.001431 | |
| Copper Wire | | | | | 0.006315 | 0.556 |
| | Copper | 7440-50-8 | 98.20 | | 0.006201 | |
| | Palladium | 7440-05-3 | 1.80 | | 0.000114 | |
| Solder Ball | | | | | 0.233980 | 20.596 |
| | Tin | 7440-31-5 | 96.50 | | 0.225791 | |
| | Silver | 7440-22-4 | 3.00 | | 0.007019 | |
| | Copper | 7440-50-8 | 0.50 | | 0.001170 | |
| Substrate | | | | | 0.384804 | 33.872 |
| | Gold | 7440-57-5 | 0.21 | | 0.000808 | |
| | Nickel | 7440-02-0 | 1.22 | | 0.004695 | |
| | Copper | 7440-50-8 | 44.30 | | 0.170468 | |
| | Glass Fiber | 65997-17-3 | 21.20 | | 0.081578 | |
| | Non halogen fire retardant | Trade Secret | 0.01 | | 0.000038 | |
| | BT Core | 105391-33-1/ 25722-66-1/ Trade Secret | 25.91 | | 0.099703 | |
| | Solder Mask | 34590-94-8/ 7727-43-7/ Trade Secret | 7.17 | | 0.027590 | |

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Revision History

The following table shows the revision history for this document.

| Date | Version | Description of Revisions |
|------------|---------|--------------------------|
| 02/15/2013 | 1.0 | Xilinx Initial Release |

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